

Call for Papers

ICEP 2022

2022 International Conference on Electronics Packaging

Date: May 11 - 14, 2022

Venue: The Sapporo Community Plaza, Hokkaido, Japan

Conference style: On-site & On-line Hybrid Conference

Please note: The conference style may be changed to Full On-Line depending on the future restrictions on travel

Sponsor: Japan Institute of Electronics Packaging (JIEP)

Technical Co-Sponsors: IEEE EPS Japan Chapter, iMAPS

Conference Topics & Special Notice for Authors

Conference Topic

- Advanced Packaging
- Design, Modeling, and Reliability
- Interconnections
- Materials & Processing
- Optoelectronics
- Power Electronics
- Thermal Management
- Highspeed, Wireless & Components
- Emerging Technologies
- Other Upcoming Technologies

On-line Poster Style

- ❑ **Short presentation** will be carried out in two ways: **1) Real time and 2) Pre-recorded.**
- ❑ **Presentation material or poster material will be shared on the web site.**
- ❑ Details will be announced on the conference web site.

Regular Presentation Style

Presentations will be carried out in two ways: 1) Real-time and 2) Pre-recorded. The authors can take either way, will be asked to choose their preference on the abstract submission, can modify the choice on the acceptance notice.

Real-time oral presentations:

- ❑ On-site presentations and discussions in certain session time
- ❑ On-site presentations (and discussions) are streamed online in real-time
- ❑ The authors will be required to submit pre-recorded presentation files for backup just in case

Pre-recorded oral presentations:

- ❑ Pre-recorded presentation videos will be played on-site and online in certain session time
- ❑ Confidentiality of the contents is on the authors
- ❑ The authors are recommended to join the real time online Q&As

OUR POLICY:

1. ICEP committee does **NOT** allow to record the presentations and discussions in **ANY WAY** to secure non-commercial public interests of an international conference.
2. The authors, except for the Keynote Lecturers and Session Invited Speakers, are **required to release the copyright** of all submitted contents in their final manuscripts. For details, visit: <https://ux.nu/o27ui>

Important Dates

Abstract submission open: September 15th, 2021
Abstract deadline: November 30th, 2021
Notification of acceptance: January 15th, 2022
Final manuscript deadline: March 7th, 2022

- Authors are encouraged to use the abstract template found at the conference website: <http://www.jiep.or.jp/icep/>
- Once the abstract is accepted, the authors will be required to prepare a **2-pages final paper**: For the final paper format, see: <http://www.jiep.or.jp/icep/>
- Accepted papers will be submitted for inclusion into IEEE Xplore as well as other Abstracting and Indexing (A&I) databases (EI Compendex and INSPEC).
- Authors are encouraged to submit their manuscripts to Transactions of The Japan Institute of Electronics Packaging, with enhanced contents of 4 – 10 pages. For details, please see: <https://www.jstage.jst.go.jp/browse/jiepeng/-char/en>

Outstanding Technical Paper Award

This award recognizes the outstanding papers presented at ICEP. The award will be given to the presenting author and co-authors of the selected papers.

Funding: The award is sponsored by JIEP.

Eligibility: The presenter must be listed as one of the authors. Conference papers must be submitted on or before the due date.

Basis: Papers are reviewed based on: Originality, technical contents, relevance, technical impact of the written paper, and the quality of the conference presentation.

IEEE EPS Japan Chapter Young Award

This award recognizes the excellent papers presented by young scientists and engineers at ICEP. This award will be given to the presenting author.

Funding: The award is sponsored by IEEE EPS Japan Chapter.

Eligibility: The presenter must be listed as the first author of their paper. The presenter must be younger than 35 years old on December 31 of the presentation year. Previous winners are not eligible. Conference papers must be submitted on or before the due date. The award recipient must be a member of IEEE and EPS at the time the award is received.

Basis: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

JIEP Poster Award

This award recognizes the excellent poster work. The award will be given to the presenting author and co-authors.

Funding: The award is sponsored by JIEP.

Eligibility: The presenter must be listed as one of their paper's authors. Conference papers must be submitted on or before the due date.

Basis: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

About ICEP

ICEP is counted as one of the largest Asian international conferences on electronic packaging, attracting more than 400 attendees and hosting over 30 technical sessions every year since 2001. This time, ICEP2022 will be held at the Sapporo Community Plaza, Hokkaido, Japan.

ICEP 2021 was in full online system with several different choices of presentation styles for global participants due to worldwide COVID-19 situation. Regarded this experience as a good opportunity to increase the choices of participation measures, ICEP2022 will take place in HYBRID style.

We sincerely hope all the attendees make the most of ICEP 2022 as a cross-cutting platform to dynamize and deepen their R&D activities.

Main Sponsor: Japan Institute for Electronics Packaging (JIEP)
Technical Co-Sponsors: IEEE Electronics Packaging Society (EPS) Japan Chapter, IMAPS

Registration Fee

The details of the registration fee will be announced in the conference HP ASAP when the conference operation style is finally decided (no later than **January 2022**).

The proceedings is included in the registration fee. How-to-get will be announced in the homepage, too.

Organizing Committee

General Chair:

Katsumi Miyama, Hokkaido University of Science

General Vice Chairs:

Tomoyuki Hatakeyama, Toyama Prefectural University
Eiji Higurashi, National Institute of Advanced Industrial Science and Technology (AIST)

Akira Yamauchi, National Institute of Technology, Gunma College

Sponsorship Opportunities

The ICEP committee intends to provide cross-disciplinary support for R&D related to electronics packaging technology and is broadly recruiting sponsors who kindly support this idea. Sponsors will receive various benefits in addition to discounted fees. The detail will be announced on the conference website soon.

Contact

ICEP 2022 secretariat (The Japan Institute of Electronics Packaging)
E-mail: icep2022@jiep.or.jp
URL: <http://www.jiep.or.jp/icep/>

